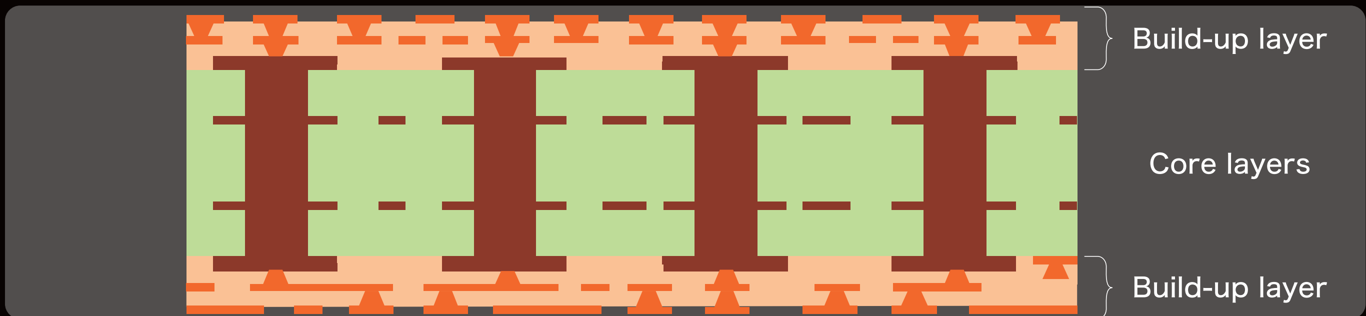
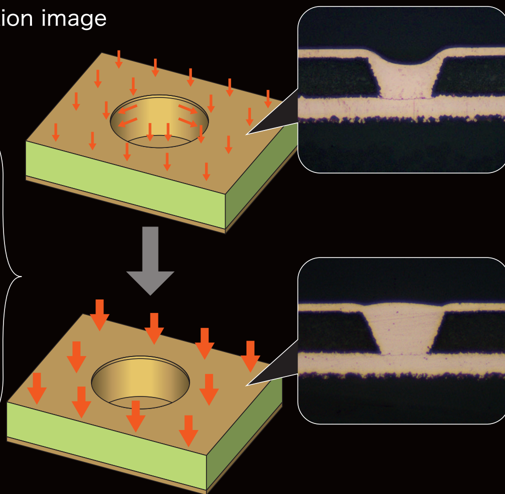
Acid copper plating additive
for large diameter vias

TOP LUCINA NSV LV

- Realize large diameter via filling
- Reduce influence by pattern width and pattern density
- Can use for through hole filling
- Can use for build-up to core layers



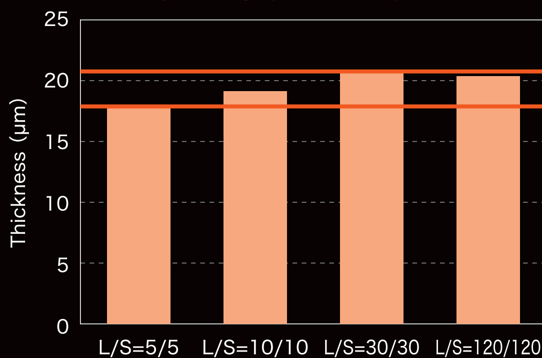
Mechanism

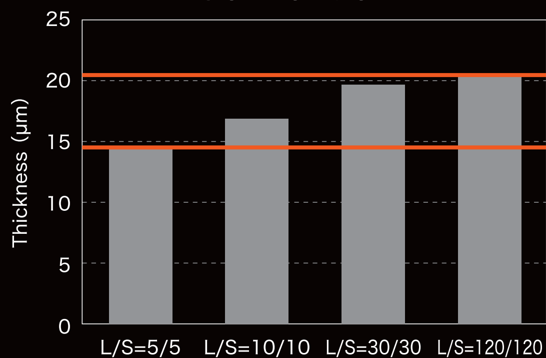


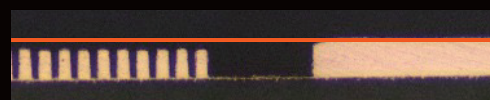
For large-diameter via and through hole filling

Via filling		Through hole filling	
Diameter	150µm	Diameter	80µm
Depth	130µm	Board thickness	200µm

Reduce influence by pattern width and pattern density







Surface thickness 18µm